ON Semiconductor



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

03-APR-2001

SUBJECT: Product/Process Change Notification #11248

TITLE: Initial Notice: Additional Die Metalization Qualification for Schottky Rectifiers

EFFECTIVE DATE: 01-Aug-2001

AFFECTED CHANGE CATEGORY: Wafer Process

AFFECTED PRODUCT DIVISION: Bipolar Discrete Products

ADDITIONAL RELIABILITY DATA: Available with Final Notification Contact your local ON Semiconductor Sales Office. or Ken Crozier <RJT440@onsemi.com>

SAMPLES: Contact Below Contact your local ON Semiconductor Sales Office. or Bob Cook <R13943@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Bob Cook <R13943@onsemi.com>

DESCRIPTION AND PURPOSE:

Initial Notification, 120 Days prior to the change will be followed by appropriate Final Process Change Notices with supporting data a minimum of 60 days prior to implementation.

ON Semiconductor has qualified an additional top and back metalization scheme for surface mount and axial leaded Schottky rectifiers. As proven through rigorous testing, the device performance and reliability is not affected. This addition will improve our manufacturing efficiency, allowing ON Semiconductor to meet the increasing demand for our Schottky rectifier product.

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QUALIFICATION PLAN:

Description: Additional solderable die metalization schemes (top and back) for our SMA, SMB, SMC, Powermite, 1A Axial, and 3A Axial Schottky product. This additional metal scheme utilizes silver, Ag, as the top layer (current scheme utilizes gold, Au).

Qualification Plan:

Test	Conditions	Exceptions
H3TRB	Tj=Max rated Tj, RH=85%, 1000 hrs.	
ESD	HBM	
HTRB	Tj=Max rated Tj, 1000 hrs.	
IOL	Ta=25 deg. C, delta Tj =>100 deg. C,	
Temp Cycle	Air to Air, -65 to 150 deg. C 1000 cycles	
Autoclave	Ta=121 deg. C, RH= 100%, PSIg= 15, 96 h	rs.
High Temp Bake	150 dec C, 1000hrs	
Bond Pull Strength	Per spec.	
Resist Solder Heat	Per spec.	
Thermal Resistance	Per Spec.	
Parametric Test	Tri Temp.	

Qualification Vehicle Justification: Top Metal / Barrier Interaction

Family/Package	Qualification Device	Reason Chosen
SMA/B/C	MBRS1100T3 (DR0966GS)	Highest Voltage in Family (100V)
Powermite/Barrier	MBRM140T3 (DR0954G)	Highest Voltage in Family (40V)
1A Surmetic(axial)	MBR1100 (DR0966G)	Highest Voltage in Family (100V)
3A Surmetic(axial)	MBR3100 (DR0968G)	Highest Voltage in Family (100V)

RELIABILITY DATA SUMMARY:

To be issued with the Final PCN.

ELECTRICAL CHARACTERISTIC SUMMARY:

To be issued with the Final PCN.

CHANGED PART IDENTIFICATION

To be issued with the Final PCN.

AFFECTED DEVICE LIST:

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1N5817 1N5817RL 1N5818 1N5818RL 1N5819 1N5819RL 1N5820 1N5820RL 1N5821 1N5821RL 1N5822 1N5822RL 80SQ045N 80SQ045NRL MBR1100 MBR1100RL MBR130P MBR130PRL MBR140PRL **MBR150** MBR150RL MBR160 MBR160RL MBR3100 MBR3100RL **MBR340** MBR340P MBR340PRL MBR340RL **MBR350** MBR350RL **MBR360** MBR360RL **MBR835** MBR835RL **MBR840** MBR840RL **MBR845** MBR845RL MBRA120LT3 MBRA130LT3 MBRA140T3 MBRM120LT3 MBRM130LT3 MBRM140T3 MBRS1100T3 MBRS120T3 MBRS130LT3 MBRS130T3 MBRS140T3 MBRS190T3 MBRS230LT3 MBRS240LT3 MBRS320T3 MBRS330T3 MBRS340T3 MBRS360T3